

SOT1880-1

plastic ultra thin fine-pitch ball grid array package; 16 balls

7 July 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	UFBGA16
Package outline version code	SOT1880-1
Manufacturer package code	SOT1880
Package type industry code	UFBGA
Package outline version description	plastic ultra thin fine-pitch ball grid array package; 16 balls
Package style descriptive code	FBGA (fine-pitch ball grid array)
Package body material type	P
Mounting method type	S (surface mount)
Security status	COMPANY PUBLIC
Issue date	16-6-2016
Customer specific indicator	N
Maturity	Product

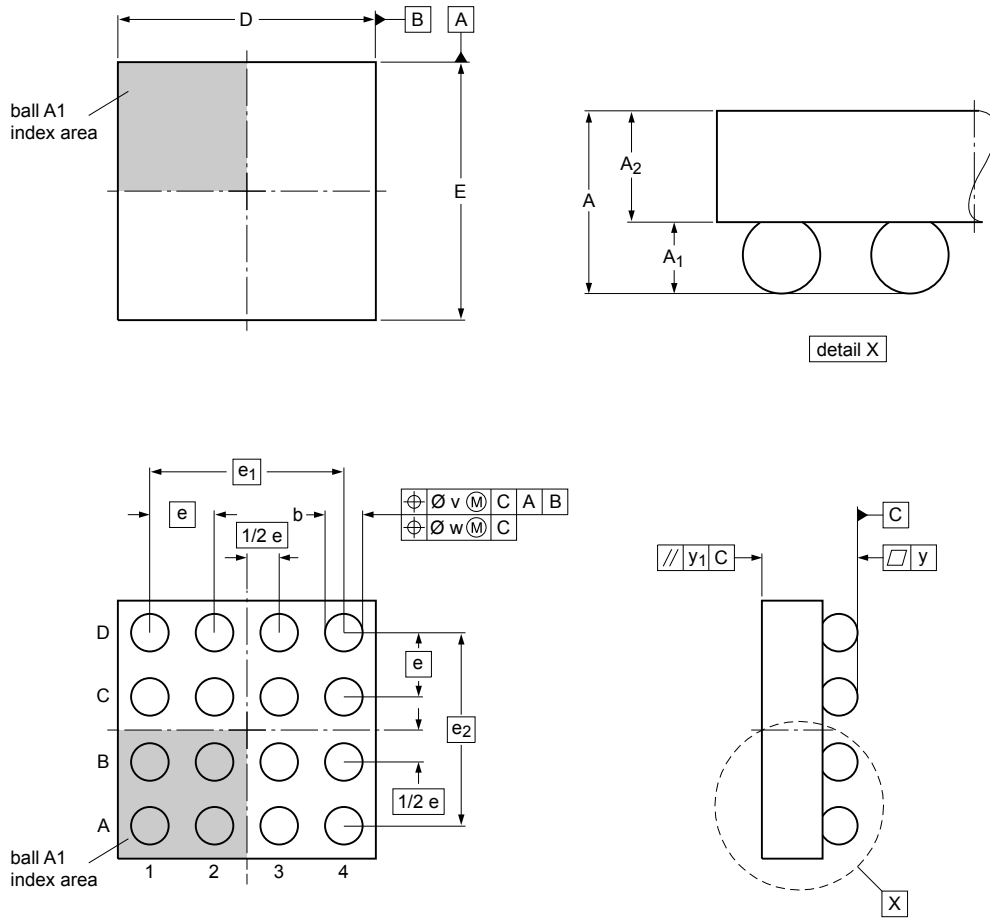
Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
A	seated height	0.5	-	0.57	0.65	m
D	package length	1.55	-	1.6	1.65	m
E	package width	1.55	-	1.6	1.65	m
e	nominal pitch	-	-	0.4	-	mm



2. Package outline

UFPGA16: plastic ultra thin fine-pitch ball grid array package; 16 balls; SOT1880-1



Dimensions

Unit	A	A ₁	A ₂	b	D	E	e	e ₁	e ₂	v	w	y	y ₁
max	0.65	0.27		0.29	1.65	1.65							
nom	0.57	0.22	0.35	0.24	1.60	1.60	0.4	1.2	1.2	0.15	0.05	0.1	0.1
min	0.50	0.17		0.19	1.55	1.55							

sot1880-1_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT1880-1		---			-16-04-15- 16-06-07

Fig. 1. Package outline UFPGA (SOT1880-1)

3. Legal information

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